



SMD 0805 + 1206 Platinum and Nickel **Thin-Film Chip Sensor**



Product

To meet the market requirements for increasingly more efficient and economical manufacturing processes, we have developed the SMD 1206 series. A platinum or nickel temperature sensor which is designed for use in markets with a high degree of automation in their production line. This thin-film sensor combines the excellent characteristics of platinum or nickel sensors such as accuracy, long-term stability and reproducibility with the advantages of large-scale production and an optimal price/performance ratio.

Advantages

- Optimised for pick-and-place machines
- Cost-effective assembling
- Easy handling
- Platinum or Nickel thin film elements
- Lead-free (acc. RoHS)



Technical Data

Nominal resistance: 100Ω . 500Ω or 1000Ω

Temperature range: -50 °C to +150 °C (1P, 2P); -50 °C to +250 °C (3P, 4P)

Classes: Pt: DIN class A; DIN class B; 2x DIN class B

Ni: DIN, ½ DIN (IST cl. A)

DIN 43760: \pm 400mK (0°C); \pm 7mK/K (>0°C); \pm 28mK/K (<0°C)

Tolerance classes: DIN class A: -50 °C to 150 °C (ref. to Pt) DIN class B: -200 °C to 250 °C

Temperature coefficient: Pt: TCR = 3850ppm/K; Ni: TCR = 6180ppm/K

Dependence of Resistivity: DIN 60751 (Platinum); former DIN 43760 (Nickel 6180ppm/K)

other resistivities on request

Soldering connection: Contacts:

1P = Contacts tin coated (62Sn/36Pb/2Ag), LMP lead contained

2P = Contacts tin coated (96.5Sn/3Ag/0.5Cu), LMP lead free, RoHS conform

3P = Contacts tin coated (5Sn/93.5Pb/1.5Ag), HMP, RoHS conform

4P* = Contacts gold plated, solderable film

*there is no ensurance for DIN class A, due to the changed resistance value

after soldering.

*bondable contacts without bumps available on request.

Solderability: 235 °C ≤ 8s (DIN IEC 68 2-20, Ta Meth 1) Resistance to soldering heat: 260 °C 10x (DIN IEC 68 2-20, Ta Meth. 1A)







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Long-term stability: Pt: max. Drift = 0.04% after 1000h at 130 ℃

Ni: max. Drift = 0.1% after 1000 h at 130 ℃

Response time: Water (0.4m/s): $T_{0.63} = 0.25s (1206)$ $T_{0.63} = 0.2s (0805)$

> Air (1m/s): $T_{0.63} = 5.0s (1206)$ $T_{0.63} = 4.0s (0805)$

The response time refers to the chip, unspoilt

Measuring current: $0.5mA (100\Omega)$; $0.4mA (500\Omega)$; $0.3mA (1000\Omega)$ Self heating: Water [mW/°C]: 40 (1206, 0805)

> Air [mW/℃]: 4 (1206, 0805)

Dimensions: Pt: 0805 (2.0 x 1.2mm); 1206 (3.2 x 1.6mm)

Ni: 1206 (3.2 x 1.6mm)

Other Nominal resistances and tolerances on request

Option for packaging: taped on reel





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